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AMENDMENTS TO THE CLAIMS

1. (**Currently amended**) A chemically amplified positive photosensitive thermosetting resin composition comprising:

a reaction product of (A) an alkali soluble resin <u>having a phenolic hydroxyl group</u> and (C) a crosslinking polyvinyl ether compound[[,]];

- (B) a compound generating an acid under irradiation with radiation[[,]]; and
- (D) an epoxy resin.
- 2. (**Original**) A chemically amplified positive photosensitive thermosetting resin composition comprising (A) an alkali soluble resin, (B) a compound generating an acid under irradiation with radiation, (C) a crosslinking polyvinyl ether compound, and (D) an epoxy resin.
- 3. (**Original**) The chemically amplified positive photosensitive thermosetting resin composition according to claim 1, which comprises a curing accelerator for the component (D).
- 4. **(Original)** The chemically amplified positive photosensitive thermosetting resin composition according to claim 3, wherein the curing accelerator is a basic compound.
- 5. (**Original**) The chemically amplified positive photosensitive thermosetting resin composition according to claim 2, which comprises a curing accelerator for the component (D).
- 6. (**Original**) The chemically amplified positive photosensitive thermosetting resin composition according to claim 5, wherein the curing accelerator is a basic compound.
- 7. (**Original**) A method for formation of a cured article, which comprises applying the chemically amplified positive photosensitive thermosetting resin composition of any one of claims 1 to 6, subjecting to prebaking, subjecting to selective exposure, subjecting to PEB (post-exposure baking) and subjecting to alkali development to form a resist pattern, followed by melting with heating and further heat curing.

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8. (**Original**) A cured article obtainable by the method of claim 7.

9. (**Original**) A method for production of a functional device, which comprises forming a resist pattern of and curing the chemically amplified positive photosensitive thermosetting resin composition of any one of claims 1 to 6.

10. (Original) A functional device obtainable by the method of claim 9.